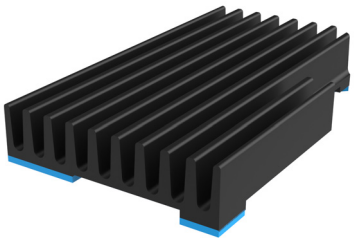
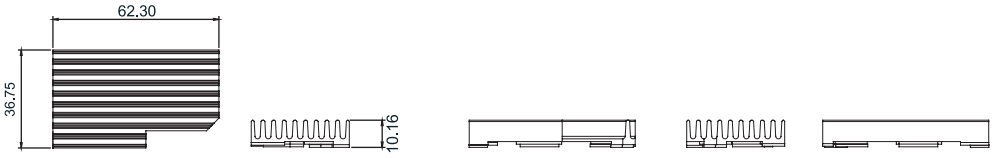
Heat-Sink
Raspberry Pi-5

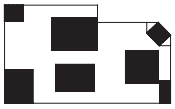


Specifications

Materials : Aluminium 6063-T5 and Thermal Transfer Pads
Finish : Black Anodised

Diagram





THERMAL TRANSFER PADS X 7 LOCATIONS

General Tolerance	
Dim.	**Tol. ±**
0 - 6	0.08
7 - 30	0.1
31 - 120	0.2

Notes:

1. General draft angle shall be 1° unless otherwise stated
2. Height of burrs should be less than 0.1mm

Dimensions : Millimetres

Part Number Table

Description	Part Number
Heat-Sink	ASM-1900181-21

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